

Title (en)
DICING DEVICE AND DICING METHOD

Title (de)
ZERTEILUNGSVORRICHTUNG UND ZERTEILUNGSVERFAHREN

Title (fr)
DISPOSITIF ET PROCÉDÉ DE DÉCOUPAGE EN DÉS

Publication
EP 2879164 B1 20170913 (EN)

Application
EP 13803775 A 20130614

Priority
• JP 2012136060 A 20120615
• JP 2013066501 W 20130614

Abstract (en)
[origin: US2015099428A1] To stably perform cutting process even on a workpiece formed from a brittle material, in a ductile mode with high precision, without causing cracking and/or breaking in the workpiece. A dicing device which performs cutting process on a workpiece includes: a dicing blade that is formed into a discoid shape from a diamond sintered body formed by sintering diamond abrasive grains, and contains 80% or more of the diamond abrasive grains; a spindle (rotating mechanism) configured to rotate the dicing blade; and a movement mechanism configured to move the workpiece relatively to the dicing blade while forming a constant cut depth on the workpiece by the dicing blade.

IPC 8 full level
H01L 21/301 (2006.01); **B24B 19/02** (2006.01); **B24B 27/06** (2006.01); **B24D 3/00** (2006.01); **B24D 3/06** (2006.01); **B24D 5/12** (2006.01); **B28D 5/00** (2006.01)

CPC (source: CN EP KR US)
B24B 9/065 (2013.01 - US); **B24B 19/02** (2013.01 - CN EP US); **B24B 27/06** (2013.01 - CN EP US); **B24D 3/00** (2013.01 - KR); **B24D 3/06** (2013.01 - KR); **B24D 5/12** (2013.01 - CN EP KR US); **B28D 5/0029** (2013.01 - EP US); **H01L 21/304** (2013.01 - KR); **H01L 21/78** (2013.01 - KR)

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
US 2015099428 A1 20150409; CN 104364884 A 20150218; CN 104364884 B 20170623; EP 2879164 A1 20150603; EP 2879164 A4 20151125; EP 2879164 B1 20170913; JP 2015164215 A 20150910; JP 5748914 B2 20150715; JP 5888827 B2 20160322; JP WO2013187510 A1 20160208; KR 102022754 B1 20190918; KR 20150004931 A 20150113; KR 20160021904 A 20160226; WO 2013187510 A1 20131219

DOCDB simple family (application)
US 201414569061 A 20141212; CN 201380031514 A 20130614; EP 13803775 A 20130614; JP 2013066501 W 20130614; JP 2014521434 A 20130614; JP 2015096460 A 20150511; KR 20147034629 A 20130614; KR 20167003252 A 20130614